

## Dual P-Channel MOSFET

-60V, -12A, 68mΩ

### FEATURES

- Fast switching
- Low thermal resistance package
- Low profile package
- Pb-free plating
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

### APPLICATION

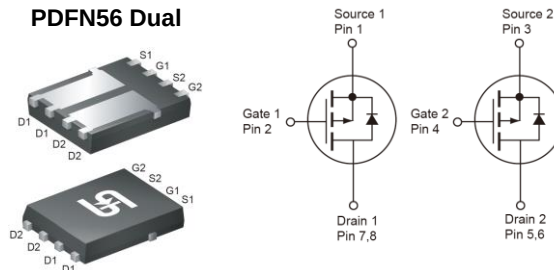
- Power Supply
- Motor Control

| KEY PERFORMANCE PARAMETERS |                  |      |
|----------------------------|------------------|------|
| PARAMETER                  | VALUE            | UNIT |
| $V_{DS}$                   | -60              | V    |
| $R_{DS(on)}$<br>(max)      | $V_{GS} = -10V$  | 68   |
|                            | $V_{GS} = -4.5V$ | 110  |
| $Q_g$                      | 16.4             | nC   |



ROHS  
COMPLIANT

HALOGEN  
FREE



Dual P-Channel MOSFET

**Note:** MSL 1 (Moisture Sensitivity Level) per J-STD-020

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

| PARAMETER                                          | SYMBOL         | LIMIT                     | UNIT             |
|----------------------------------------------------|----------------|---------------------------|------------------|
| Drain-Source Voltage                               | $V_{DS}$       | -60                       | V                |
| Gate-Source Voltage                                | $V_{GS}$       | $\pm 20$                  | V                |
| Continuous Drain Current (Note 1)                  | $I_D$          | $T_C = 25^\circ\text{C}$  | A                |
|                                                    |                | $T_C = 100^\circ\text{C}$ |                  |
| Pulsed Drain Current (Note 2)                      | $I_{DM}$       | -48                       | A                |
| Total Power Dissipation @ $T_C = 25^\circ\text{C}$ | $P_{TOT}$      | 3.5                       | W                |
| Single Pulsed Avalanche Energy (Note 3)            | $E_{AS}$       | 7.2                       | mJ               |
| Single Pulsed Avalanche Current (Note 3)           | $I_{AS}$       | 12                        | A                |
| Operating Junction and Storage Temperature Range   | $T_J, T_{STG}$ | - 55 to +150              | $^\circ\text{C}$ |

### THERMAL PERFORMANCE

| PARAMETER                              | SYMBOL          | LIMIT | UNIT               |
|----------------------------------------|-----------------|-------|--------------------|
| Junction to Case Thermal Resistance    | $R_{\theta JC}$ | 4.5   | $^\circ\text{C/W}$ |
| Junction to Ambient Thermal Resistance | $R_{\theta JA}$ | 85    | $^\circ\text{C/W}$ |

**Notes:**  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\theta JA}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.  $R_{\theta JA}$  shown below for single device operation on FR-4 PCB in still air

**ELECTRICAL SPECIFICATIONS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

| PARAMETER                                             | CONDITIONS                                                              | SYMBOL              | MIN  | TYP  | MAX  | UNIT |
|-------------------------------------------------------|-------------------------------------------------------------------------|---------------------|------|------|------|------|
| Static <sup>(Note 4)</sup>                            |                                                                         |                     |      |      |      |      |
| Drain-Source Breakdown Voltage                        | V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA                           | BV <sub>DSS</sub>   | -60  | --   | --   | V    |
| Gate Threshold Voltage                                | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA             | V <sub>GS(TH)</sub> | -1.2 | -1.6 | -2.5 | V    |
| Gate Body Leakage                                     | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V                            | I <sub>GSS</sub>    | --   | --   | ±100 | nA   |
| Zero Gate Voltage Drain Current                       | V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0V                            | I <sub>DSS</sub>    | --   | --   | -1   | μA   |
|                                                       | V <sub>DS</sub> = -48V, T <sub>c</sub> = 125°C                          |                     | --   | --   | -10  |      |
| Drain-Source On-State Resistance                      | V <sub>GS</sub> = -10V, I <sub>D</sub> = -6A                            | R <sub>DS(on)</sub> | --   | 54   | 68   | mΩ   |
|                                                       | V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3A                           |                     | --   | 90   | 110  |      |
| Forward Transconductance                              | V <sub>DS</sub> = -10V, I <sub>D</sub> = -6A                            | g <sub>fs</sub>     | --   | 8.5  | --   | S    |
| Dynamic <sup>(Note 5)</sup>                           |                                                                         |                     |      |      |      |      |
| Total Gate Charge                                     | V <sub>DS</sub> = -30V, I <sub>D</sub> = -6A,<br>V <sub>GS</sub> = -10V | Q <sub>g</sub>      | --   | 16.4 | --   | nC   |
| Gate-Source Charge                                    |                                                                         | Q <sub>gs</sub>     | --   | 2.8  | --   |      |
| Gate-Drain Charge                                     |                                                                         | Q <sub>gd</sub>     | --   | 3.6  | --   |      |
| Input Capacitance                                     | V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V,<br>f = 1.0MHz             | C <sub>iss</sub>    | --   | 870  | --   | pF   |
| Output Capacitance                                    |                                                                         | C <sub>oss</sub>    | --   | 70   | --   |      |
| Reverse Transfer Capacitance                          |                                                                         | C <sub>rss</sub>    | --   | 42   | --   |      |
| Switching <sup>(Note 6)</sup>                         |                                                                         |                     |      |      |      |      |
| Turn-On Delay Time                                    | V <sub>DD</sub> = -30V, I <sub>D</sub> = -1A,<br>R <sub>GEN</sub> =6Ω   | t <sub>d(on)</sub>  | --   | 8.3  | --   | ns   |
| Turn-On Rise Time                                     |                                                                         | t <sub>r</sub>      | --   | 42.4 | --   |      |
| Turn-Off Delay Time                                   |                                                                         | t <sub>d(off)</sub> | --   | 64.6 | --   |      |
| Turn-Off Fall Time                                    |                                                                         | t <sub>f</sub>      | --   | 16.4 | --   |      |
| Source-Drain Diode <sup>(Note 4)</sup>                |                                                                         |                     |      |      |      |      |
| Maximum Continuous Drain-Source Diode Forward Current | Integral reverse diode in the MOSFET                                    | I <sub>S</sub>      | --   | --   | -12  | A    |
| Maximum Pulse Drain-Source Diode Forward Current      |                                                                         | I <sub>SM</sub>     | --   | --   | -48  | A    |
| Diode-Source Forward Voltage                          | V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A                              | V <sub>SD</sub>     | --   | --   | -1   | V    |

**Notes:**

- Current limited by package
- Pulse width limited by the maximum junction temperature
- $L = 0.1\text{mH}, I_{AS} = -12A, V_{DD} = -25V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse test:  $PW \leq 300\mu s$ , duty cycle  $\leq 2\%$
- For DESIGN AID ONLY, not subject to production testing.
- Switching time is essentially independent of operating temperature.

**ORDERING INFORMATION (EXAMPLE)**

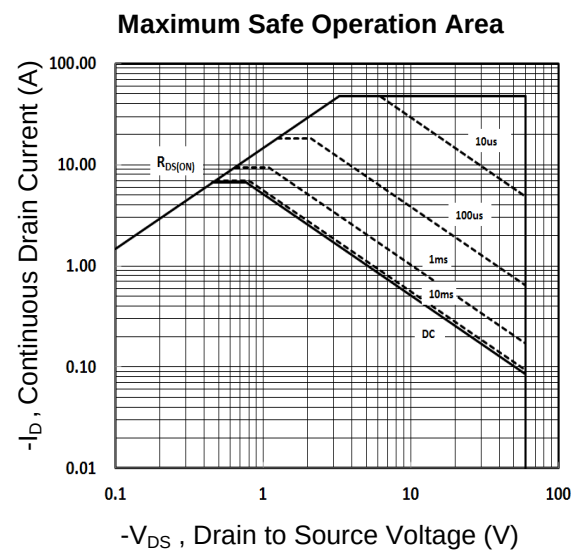
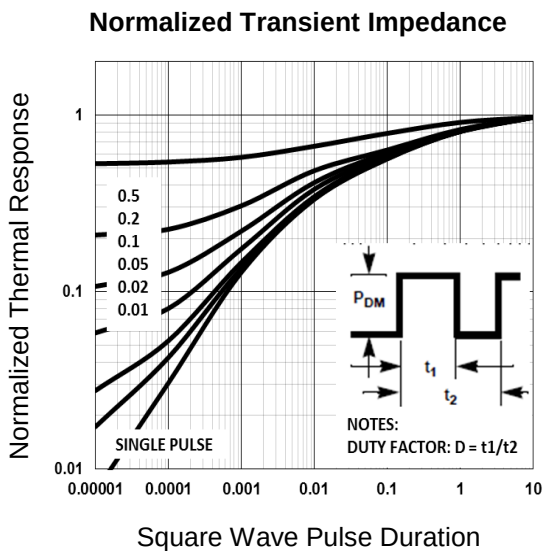
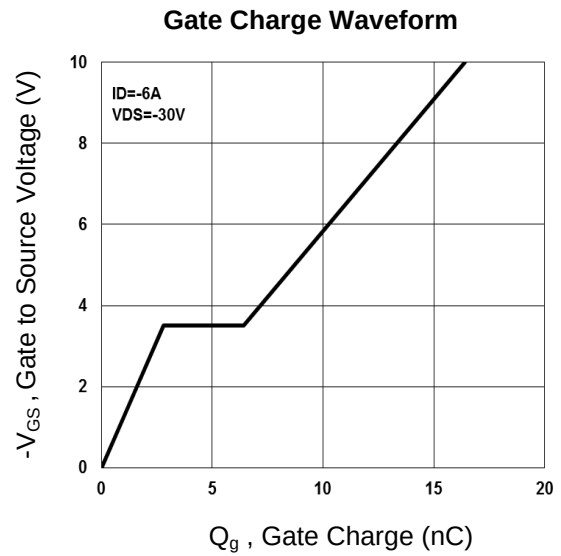
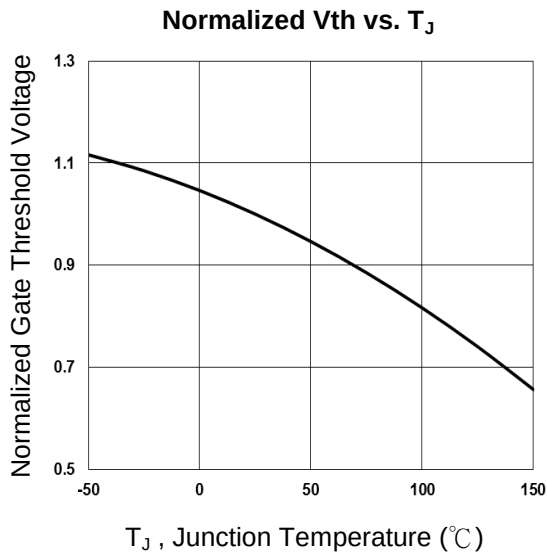
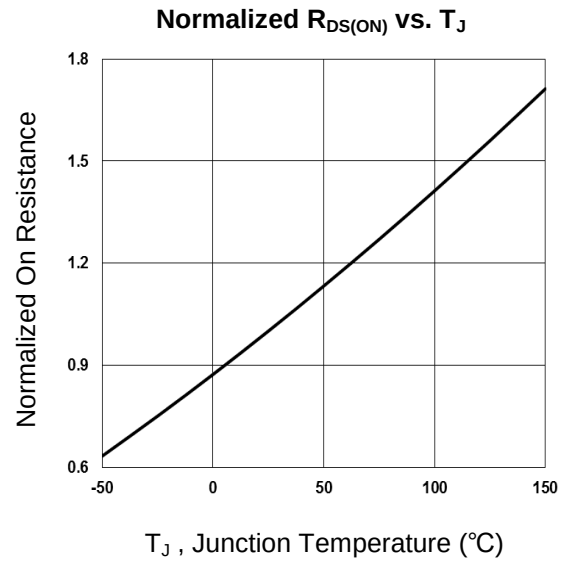
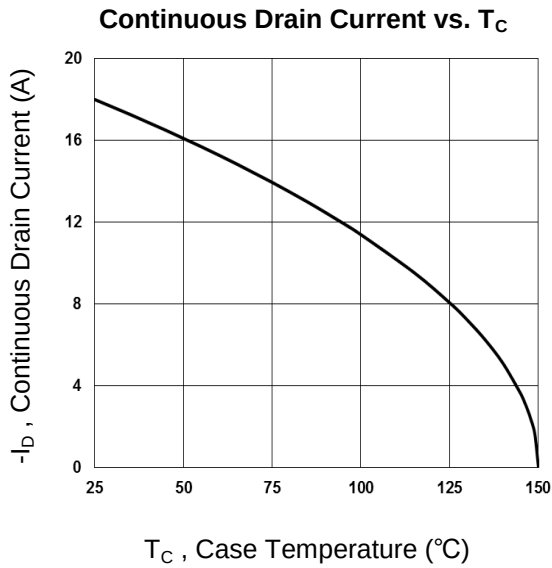
| PART NO.           | PACKAGE     | PACKING            |
|--------------------|-------------|--------------------|
| TSM680P06DPQ56 RLG | PDFN56 Dual | 2,500pcs / 13"Reel |

**Note:**

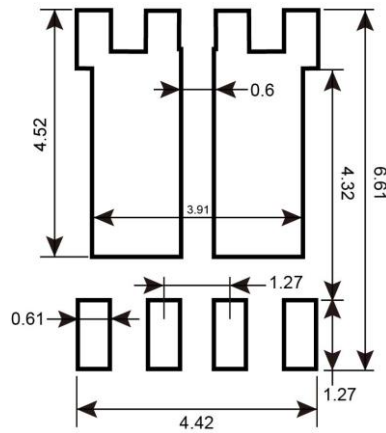
1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
2. Halogen-free according to IEC 61249-2-21 definition

## CHARACTERISTICS CURVES

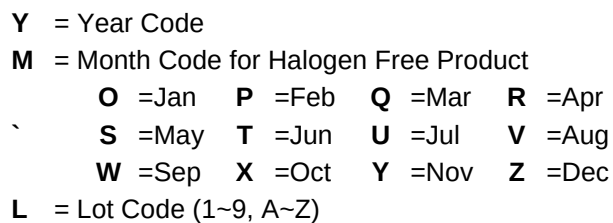
( $T_C = 25^\circ\text{C}$  unless otherwise noted)



## PDFN56 Dual



## MARKING DIAGRAM



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